

ABSTRACT

A slurry removal control mechanism for a CMP polisher is provided. After slurry dispense has been terminated, a high pressure fluid spray removes the slurry from the polishing pad, while the platen causes the pad to rotate at a high rpm rate, thus clearing the slurry from contact with the wafer. Additionally, there is provided a slurry dispense bar including high pressure spray nozzles for providing a high pressure spray upon slurry dispense termination.